

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1. – 36. (Canceled).

37. (Currently Amended) A process for the production of a wiring board, comprising the steps of:

defining an opening at a predetermined position of a film-like insulating substrate;

forming a conductive thin film on a first principal surface ~~plane~~ of said insulating substrate;

etching said conductive thin film to form an electric wiring provided with a connection terminal covering said opening; and

forming, in said opening, a conductive member that is connected to said connection terminal, ~~having a thickness equal to or thinner than that of said insulating substrate.~~

wherein said conductive member does not protrude from a second principal surface of said insulating substrate opposed to said first principal surface and has a thickness thinner than that of said insulating substrate.

38. (Currently Amended) A process for the production of a wiring board, comprising the steps of:

defining an opening at a predetermined position of a film-like insulating substrate;

forming a conductive thin film on a first principal surface ~~plane~~ of said insulating substrate;

etching said conductive thin film to form an electric wiring provided with a connection terminal covering said opening;

forming, in said opening, a conductive member that is connected to said connection terminal ~~having a thickness equal to or thinner than that of said insulating substrate~~; and

forming sequentially a thin film layer made of nickel (Ni) and a thin film layer made of gold (Au) on the surfaces of said ~~electric wiring and said~~ conductive member ~~[[.]]~~,

wherein said conductive member does not protrude from a second principal surface of said insulating substrate opposed to said first principal surface and has a thickness thinner than that of said insulating substrate, and said thin film layer made of gold does not protrude from said second principal surface.

39. **(Currently Amended)** A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with an electroplating method.

40. **(Currently Amended)** A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with an electroplating method.

41. **(Currently Amended)** A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with an electroless plating method.

42. **(Currently Amended)** A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with an electroless plating method.

43. **(Original)** A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by such a manner that the inside of said opening is filled with a conductive paste of silver (Ag) or copper (Cu), and said conductive paste is solidified.

44. **(Original)** A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by such a manner that the inside of said opening is filled with a conductive paste of silver (Ag) or copper (Cu), and said conductive paste is solidified.

45. **(Original)** A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.

46. **(Original)** A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.

47. (Original) A process for the production of a wiring board as claimed in claim 39, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.

48. (Original) A process for the production of a wiring board as claimed in claim 41, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.

49. (Original) A process for the production of a wiring board as claimed in claim 43, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.